

In the Claims:

1. (Currently amended) A method of fabricating an ink jet nozzle arrangement on a wafer, the method comprising the steps, ~~which can be carried out in any suitable order~~, of:
- ~~providing a wafer;~~
- ~~depositing a resistive heating material and a thermal expansion material on the wafer and~~
- ~~etching a plurality of permanent layers the heating and thermal expansion material to form a thermo-electrical actuator of a micro-electromechanical ink ejection mechanism on one side of the wafer to form an a micro-electromechanical ink ejection mechanism ;~~
- anisotropically wet etching said wafer from said one side to form a nozzle chamber; and
- etching said wafer from an opposed side to form an ink supply channel in communication with the nozzle chamber for supplying ink to the nozzle chamber.
2. (Original) The method of claim 1 in which the wet etching includes crystallographically etching the wafer along predetermined planes.
3. (Original) The method of claim 2 which includes crystallographically etching the wafer along  $\langle 111 \rangle$  planes.
4. (Original) The method of claim 1 which includes plasma etching the wafer from said opposed side.
5. (Original) The method of claim 4 which includes using an anisotropic etcher for plasma etching the wafer.
6. (Currently amended) The method of claim 1 in which the step of etching the wafer from said opposed side also ~~does~~ incorporates the step of dicing the wafer.